

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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NOTES:

1) MATERIAL:  
 HOUSING & INSULATOR: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: BLACK  
 TERMINALS: PHOSPHOR BRONZE, .012/(0.30) THICK  
 SHIELD: BRASS

2) FINISH:  
 TERMINALS:  
 A = SELECT GOLD IN CONTACT AREA: .000050/(0.00127) MIN.,  
 \*SELECT MATTE TIN IN PC TAIL AREA: .000100/(0.00254) MIN.,  
 WITH OVERALL NICKEL UNDERPLATE: .000050/(0.00127) MIN.  
 B = SELECT GOLD IN CONTACT AREA: .000030/(0.00076) MIN.,  
 \*SELECT MATTE TIN IN PC TAIL AREA: .000100/(0.00254) MIN.,  
 WITH OVERALL NICKEL UNDERPLATE: .000050/(0.00127) MIN.  
 C = SELECT GOLD IN CONTACT AREA: .000015/(0.00038) MIN.,  
 \*SELECT MATTE TIN IN PC TAIL AREA: .000100/(0.00254) MIN.,  
 WITH OVERALL NICKEL UNDERPLATE: .000050/(0.00127) MIN.

SHIELD:  
 \*100 MICRONS NICKEL OVER 50 MICRONS COPPER UNDERPLATE  
 PCB GROUND TABS DIPPED IN TIN  
 \*THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS  
 DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC".  
 CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH TIN-LEAD  
 IN THE PC TAILS AND/OR SHIELD.

3) PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43743-0001.

4) PACKAGING SPECIFICATION:  
 CONNECTOR ASSEMBLIES TO BE PACKAGED USING TAPE & REEL SYSTEM  
 PER PACKAGING DRAWING PK-70873-7006.

5) COPLANARITY SPECIFICATION:  
 WHEN AN ASSEMBLY IS PLACED UPON A LEVEL SURFACE, THE MAXIMUM  
 GAP BETWEEN THE LEVEL SURFACE AND ALL TERMINAL TAILS AND  
 FRONT SOLDER TAB IS .006/(0.15).

6) THRU HOLES .094±.002/(2.39±0.05) ARE FOR SHIELDS WITH LOCATION TABS ONLY.

7) AVAILABLE WITH (4) OPTIONAL SIDE GROUND TABS (OMITTED FOR SIDE TO SIDE  
 STACKABILITY).

8) AVAILABLE WITH (2) OPTIONAL LOCATION TABS FOR LOCATING COMPONENT  
 TO PCB AND/OR GROUNDING TO PCB.

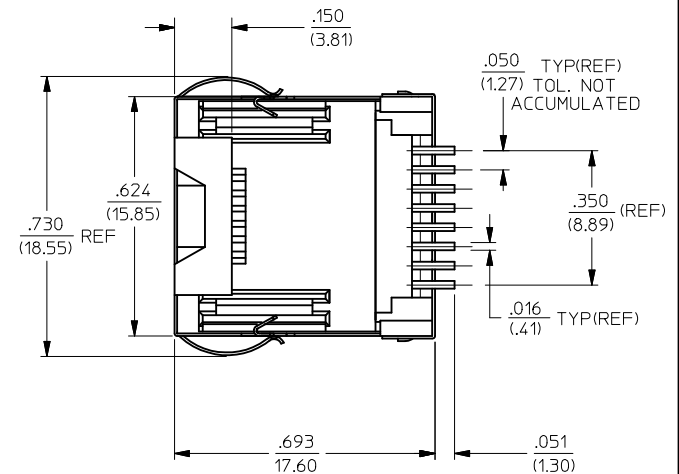
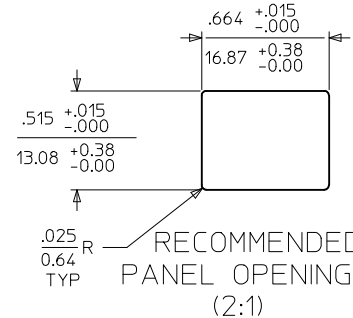
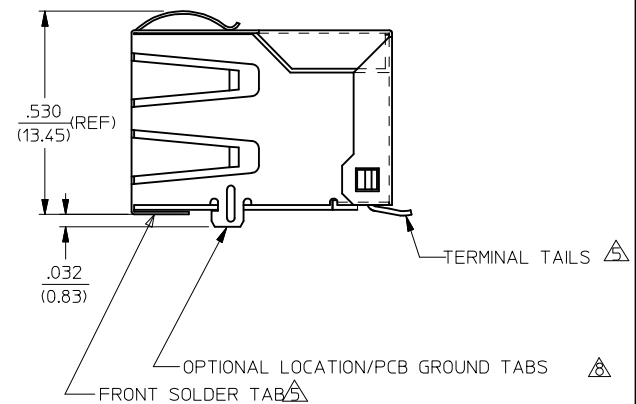
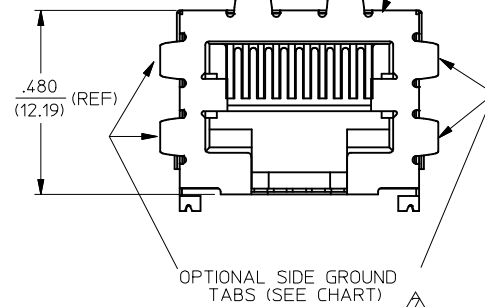
9) FOR ASSEMBLIES HAVING VOIDED CIRCUITS, THE TAIL PORTION IS CUT  
 AND REMOVED. THE MATING PORTION OF THE TERMINAL REMAINS INTACT.

10) CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.

11) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC  
 SPECIFICATION PS-45499-002.

OPTIONAL TOP GROUND TABS  
 (SEE CHART)

SHIELDED SMT  
 MODJACK ASSEMBLY



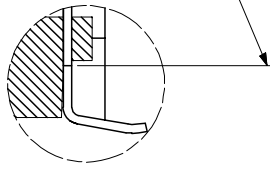
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44282-0012	C	NO	YES	NO	NONE
44282-0011	B	NO	YES	NO	NONE
44282-0010	A	NO	YES	NO	NONE
44282-0009	C	YES	YES	NO	NONE
44282-0008	B	YES	YES	NO	NONE
44282-0007	A	YES	YES	NO	NONE
44282-0006	C	NO	YES	YES	NONE
44282-0005	B	NO	YES	YES	NONE
44282-0004	A	NO	YES	YES	NONE
44282-0003	C	YES	YES	YES	NONE
44282-0002	B	YES	YES	YES	NONE
44282-0001	A	YES	YES	YES	NONE

44282-0001, 44282-0002  
 & 44282-0003 SHOWN

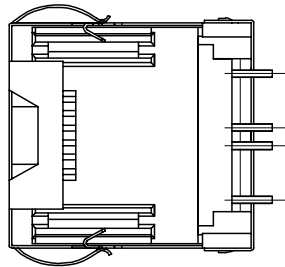
REVISED NOTES EC NO: UCP2009-1244 DRWN:JKLOSTEMEIER 2008/12/10 CHKD:JBELL 2008/12/10 APPR:FSMITH 2008/12/10	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± .010 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± --- ANGULAR ± 1/2°	DIMENSION STYLE IN/MM DRAWN BY STAMBAUG DATE 99/06/03 CHECKED BY WIRKUS DATE 99/06/03 APPROVED BY EDGLEY DATE 99/06/03	SCALE 1:1 DESIGN UNITS INCH THIRD ANGLE PROJECTION	TITLE SINGLE PORT, SHIELDED SIZE 8, 8 CIRCUIT SMT MODJACK	MATERIAL NO. SEE CHART	DOCUMENT NO. SD-44282-001	SHEET NO. 1 OF 2
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MOLEX INCORPORATED		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
	D3		SIZE C		2 D2 1 D3 SHT REV			
	REV		DESCRIPTION		12 11 10 9 8 7 6 5 4 3 2 1			

13 12 11 10 9 8 7 6 5 4 3 2 1

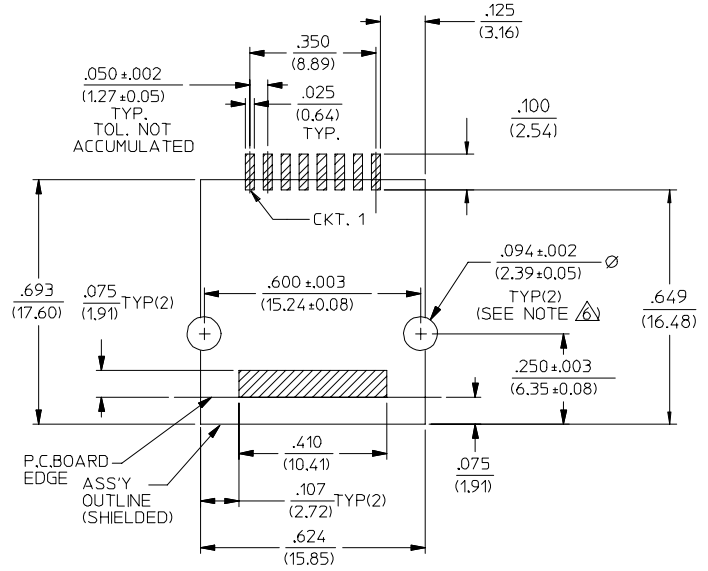
TERMINAL CUTOFF POINT



VIEW SHOWING TYPICAL TERMINAL CUTOFF OF TAIL (SEE NOTE 10) FOR VOIDED CIRCUITS.



TYPICAL VIEW SHOWING VOIDED CIRCUIT (CIRCUITS 2,3,6 & 7 SHOWN VOIDED)



PC BOARD LAYOUT FOR 8 POSITION HOUSING  
(COMPONENT SIDE OF BOARD)

NOTES:  
1. RECOMMENDED MINIMUM PCB THICKNESS: .034/0.86

SEE SHEET ONE FC NO: UCP2008-0143 DRAWN: JBELL 2007/07/24 CHKD: LSJHMI DT 2007/07/30 APPR: FSM TH 2007/08/01 D2	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE IN/MM		SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION		
		mm	INCH	DRAWN BY	DATE	TITLE				
		4 PLACES ± .010	± .010	STAMBAUG	99/06/03	SURFACE MOUNT MODULAR JACK W/ SHIELD				
		3 PLACES ± .025	± .025	CHECKED BY	DATE	MOLEX INCORPORATED				
2 PLACES ± .050	± .050	WIRKUS	99/06/03	APPROVED BY		DATE	SD-44282-001			
1 PLACE ± .100	± .100	EDGLEY	99/06/03	MATERIAL NO.		DOCUMENT NO.	SHEET NO.			
ANGULAR ±1/2°		SEE CHART		SD-44282-001		2 OF 2				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

12 11 10 9 8 7 6 5 4 3 2 1